PATENT

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Warren M. Farnworth

**Serial No.:** 10/043,468

**Filed:** January 10, 2002

**For:** METHOD OF FORMING OVERMOLDED CHIP SCALE PACKAGE AND RESULTING PRODUCT

**Confirmation No.:** 7094

**Examiner:** K. Nguyen

**Group Art Unit:** 2823

**Attorney Docket No.:** 2269-3085.4US
(96-1033.04/US)

**Notice of Allowance Mailed:**

January 2, 2004

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

March 19, 2004
Date

Doreen Neumann
Signature

Doreen Neumann
Name (Type/Print)

## TRANSMITTAL LETTER

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant submits herewith Part B - Fee(s) Transmittal for the above-captioned application and a check in the amount of $1,645.00 in payment therefor plus five (5) copies of the patent when issued.

Also enclosed are Amendment Pursuant to 37 C.F.R. § 1.312(a); Comments on Statement of Reasons for Allowance; and Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees.

Applicant understands that no additional fees are required. However, if the Office determines that any comparison fees or other additional fees are required, the Commissioner is authorized to charge any such fees to TraskBritt Deposit Account No. 20-1469. A copy of this Transmittal Letter is enclosed for deposit account charging purposes.

Respectfully submitted,

Edgar R. Cataxinos
Registration No. 39,931
Attorney for Applicant
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: March 19, 2004
ERC/dlm:dn
Enclosures: Part B - Issue Fee Transmittal
Check No. 20073 in the amount of $1,645.00
Copy of Transmittal Letter
Amendment Pursuant to 37 C.F.R. § 1.312(a) (17 pages)
Comments on Statement of Reasons for Allowance (2 pages)
Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages)

Document in ProLaw

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## COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Mail Stop Issue Fee
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

The Examiner indicates:

The prior art taken alone or in combination neither discloses nor makes obvious the instant process of claims as a whole. Specifically, the prior art of record, Akagawa (U.S. Patent 5,677,576) discloses a method for forming a semiconductor wafer (FIG. 1: 32) having an active surface, the active surface having bond pads (FIG. 1: 36) thereon, the method comprising: forming conductive traces (FIG 1: 40) over the active surface, each of the conductive traces having a first end, a second end, a top surface, and a bottom surface wherein the bottom surface of the first end of each conductive trace being in contact with at least one of the bond pads (col. 3, lines 10-39), forming a conductive bump (FIG. 1: 46) on the top

surface at the second end of the conductive traces wherein the conductive bump having a top portion transverse to the top surface of the conductive traces (col. 3, lines 58-60, and forming a layer of encapsulation material (FIG. 1: 42) to cover the active surface of the semiconductor wafer and to surround the conductive bump (col. 3, lines 47-48) but fails to teach or suggest the Applicant's steps of planarizing the top portion of the conductive bump, forming a layer of encapsulation material to cover the active surface of the semiconductor wafer and to surround the planarized conductive bump, and reforming the conductive bump to a preplanarized shape extending above the layer and away from at least portion of the encapsulation material adjacent to the conductive bump as recited in the amended independent claims.

Applicant concurs with the reasons as stated by the Examiner insofar as they comprise a summary, and are exemplary and not limiting. However, the independent claims as allowed include other and different language than that specified by the Examiner, and the allowed dependent claims include other and further features and elements. Accordingly, the scope of the claims must be determined from the literal language of each as a whole, as well as equivalents thereof.

Respectfully submitted,

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